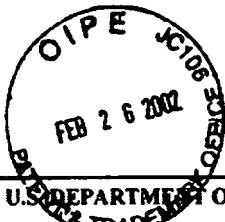


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Form PTO-1449 (REV. 07/01)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. INDUM-108XX		APPLICATION NO. 10/008,853	
INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				APPLICANT: Wusheng Yin, et al.			
				FILING DATE 11/15/01		GROUP 2811	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE*
PAZ		5,128,746	7/7/92	Pennisi et al	357	72	
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PAZ		WO 99/56312	11/4/99				
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PAZ	A Novel Approach to Incorporate Silica Filler into No-Flow Underfill, Zhuqing Zhang, et al., School of Materials Science and Engineering and Packaging Research Center, Georgia Institute of Technology, Atlanta, GA, pp. 1-7.						
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EXAMINER 				DATE CONSIDERED 7/15/03			
*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							



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APPLICANT:

Wusheng Yin, et al.

FILING DATE
11/16/01GROUP
2811

U.S. PATENT DOCUMENTS

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	<u>Surface Mount Technology, Materials, Processes and Equipment</u> , Carment Capillo, UNISYS Corporation, Network Computing Group, San Jose, CA, McGraw-Hill Publishing Co.
	<u>Epoxy Flip Chip Flux PK-001</u> , Indium Corporation of America, Form No. 97727 R0.
	<u>Pb-Free Epoxy Flip Chip Flux PK-002</u> , Indium Corporation of America, Form No. 97728 R0.

EXAMINER

DATE CONSIDERED

7/15/3

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